

IN THE CLAIMS

Claims 1-13 (Canceled).

14 (Previously Presented). A method comprising:

forming a trench in an integrated circuit substrate;
lining the trench with a catalyst material to remove gases from a circulating fluid;
forming channels that align with said trench to allow fluid circulation completely
across said substrate from one side of said substrate to the other and through said trench; and
protecting said catalyst when forming said channels.

Claim 15 (Canceled).

16 (Original). The method of claim 14 including depositing platinum as said catalyst in
said trench.

17 (Previously Presented). The method of claim 14 including depositing lead in said
trench as said catalyst.

Claims 18-21 (Canceled).